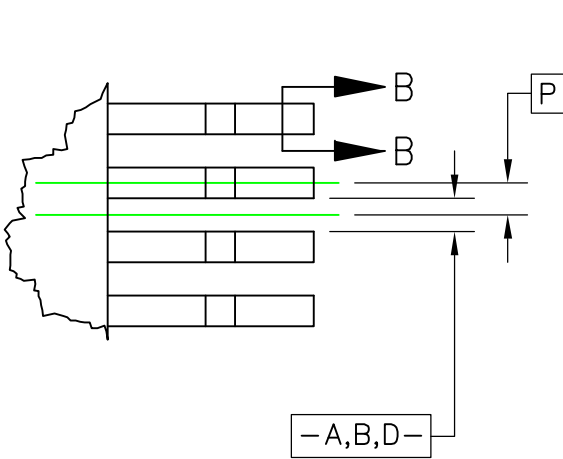
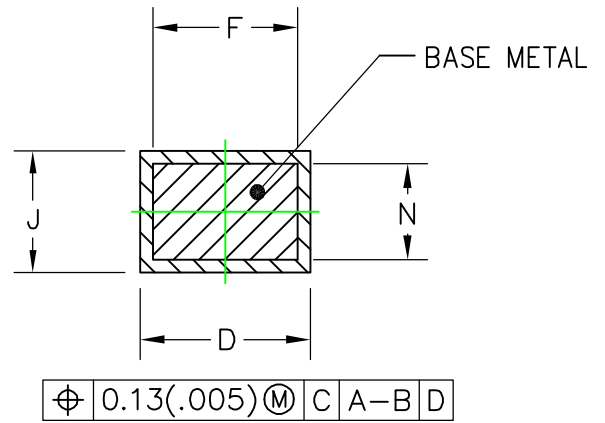


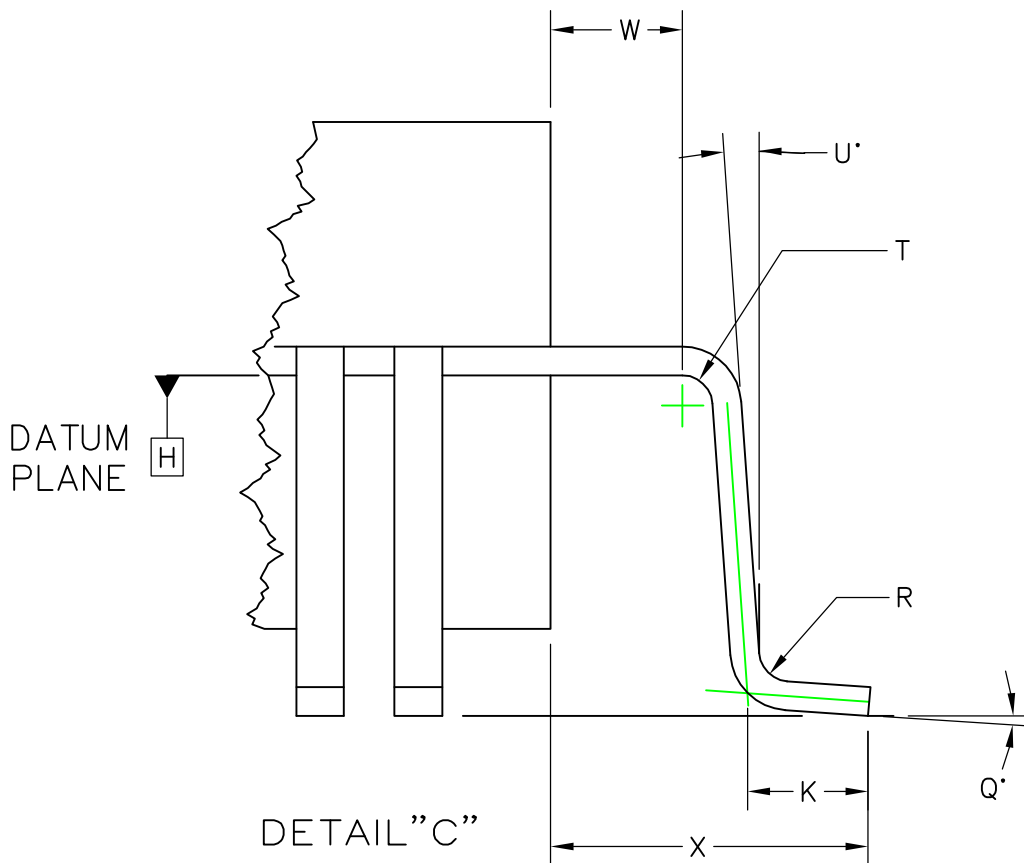
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TITLE: CQFP 184 LEAD 31 X 31 X 3.5 0.65 MM PITCH	DOCUMENT NO: 98ASS23138W		REV: D
	STANDARD: NON-JEDEC		
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DETAIL A



SECTION B-B



DETAIL "C"

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1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
6. DIMENSIONS A AND B DEFINE MAXIMUM CERAMIC BODY DIMENSIONS INCLUDING GLASS PROTRUSION AND MISMATCH CERAMIC BODY TOP AND BOTTOM.

DIM	MILLIMETER		INCH		DIM	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	30.860	31.750	1.215	1.250	Q	0°	8°	0°	8°
B	30.860	31.750	1.215	1.250	R	0.200 REF		0.008 REF	
C	3.280	4.880	0.129	0.192	S	35.000	35.400	1.378	1.394
D	0.220	0.410	0.009	0.016	T	0.200 REF		0.008 REF	
E	3.030	4.000	0.120	0.157	U	0°	8°	0°	8°
F	0.220	0.330	0.009	0.12	V	35.000	35.400	1.378	1.394
G	0.650 BSC		0.0256 BSC		W	0.800 REF		0.031 REF	
H	0.250	0.880	0.010	0.035	X	2.100 REF		0.083 REF	
J	0.127	0.250	0.005	0.010	Y	0.750 REF		0.030 REF	
K	0.650	0.950	0.026	0.037	Z	0.750 REF		0.030 REF	
L	29.250 REF		1.152 REF						
N	0.122	0.203	0.005	0.008					
P	0.325 BSC		0.0128 BSC						

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